

SEALING RESIN USED FOR COMPRESSION MOLDING, AND FORMING METHOD
FOR SAME

ABSTRACT

The present invention addresses the problem of providing a sealing resin and a forming
5 method for the same with which it is possible to achieve a compression molding device and a
compression molding method capable of preventing the occurrence of molding defects. As the
means for solving the problem, a sealing resin (R) according to the present invention is used in
the compression molding of a workpiece (W) having a configuration in which an electronic
component (Wb) is mounted on a base material (Wa), the sealing resin including a plate-shaped
10 or block-shaped body (Ra), and legs (Rb) provided upright on one surface of the body (Ra), and
the sealing resin being formed in a shape that does not make contact with the electronic component
(Wb) when mounted on the base material (Wa).

Representative drawing: FIG. 8